

ABSTRACT

When applying a flux 2 kept in a container 16 onto a conductive ball 1, the flux 2 is first applied by a squeegee unit 17 on a bottom 16a of container 16 in the form of layer having a certain predetermined layer thickness. Then, a suction head 20 holding a solder ball 1 is lowered towards the container 16. As soon as a touch sensor 43 detects a touching of the solder ball 1 to the bottom 16a, the suction head 20 is lifted, and the solder ball 1 held to the suction head 20 is transferred onto a workpiece. Thus a solder ball 1 may be transferred onto a workpiece after being applied with a certain specific amount of flux 2 with precision.

Fig. 3

THIS SHEET HAS BEEN
REPLACED

This Sheet Has Been Replaced

